**Minutes – 130818**

**Present: HH, SW, DS, TJ, PD, IT, YG**

**Apologies: AG, SB, JT,**

**Strip modules**

Tooling review is ongoing. So far no comments. Discussion with ankush about 12 module chuck thing. Sven thinks it may not work. AG did work on new pcb – but now on holiday. Sven to build the new module this week. Alibaba measurement of irradiated sensors (LSS qualification. Deadline is for market survey.)

Sent 5 cm sensors we cannot readout using Alibaba. Sven to send back.

Clean room closed Thursday- Monday.

**Strip Mechanics**

Need to start making stave. Discuss with Hamish. Hamish doing humidity tests. He spilt water in box.

One test with glue before assembly.

Priority is to not miss the “planer slot”. Need to discuss with Kevin. – get estimate when he can do this.

*Tooling: now able to make stave vacuum jig out of aluminium. Priority to get this done by October. Kevin to do machining. PS to order material and work on design before he goes away. Ask Kevin about design of middle to prevent bending.*

TJ discussed with TW. – As long as top surface correct to +/- 100 micron should be ok . this week PS to talk to Kevin as to whether this achievable in large piece aluminium. TJ to ask PS to consider design like Sven’s : thick top, thin bottom.

**Pixel modules**

IT make 6 boxes on Friday, 4 this morning. 2 more boxes to go. 6 boxes for Glasgow, 6 for oxford. We will make as we go. Make lids tomorrow morning.

RB promised us silicon weeks ago, CB promised on thursday. IT also asked for bare chips as well. ----IT to go to Glasgow on Wednesday – collect items.

IT posted vacuum chucks to oxford and Glasgow.

Glue: IT will try glue today. Try to adapt stamping method, Increase glue thickness to 30- 50 micron. Sponge with mesh on top. -> try today. If works present tomorrow.

Try stamping a few times to study consistency of glue thickness. IT also has dummies to check for glue “flooding”

YG: present on Thursday (UK) before presenting to CERN (Tuesday meeting).

We should be getting 4 modules to make. Awaiting for CB to give greenlight on production. We are still waiting for hybrids being bent in Glasgow. Should arrive next week.

Q: is MW around next week?

Plan is to build one module -> test it is ok (with RCE) , then build next 3.

The enclosure has arrived for the test box.

IT to make poster. Send to Eva for approval.

PD: interlock stuff is getting close. Still a question on the LV.

Half ring frame should arrive today. IT/Akhil to design interface boards.

Q what is happening with irradiated modules?

Status of DAQ: Timon replied about firmware. Need a chip to test. Get it on Wednesday. Missing RD53 chip to test.

**Pixel Mechanics**

Have quotes for CF – much more expensive that we originally though. We are now asking for cyanate ester

Do we really need the expensive one? We have experience through the face sheets.

**AOB**

HH-> get pizza night date.